

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD50P04P4-13	**Issued**	24. February 2022
MA#	MA005709158		
Package	PG-TO252-3-313	**Weight***	318.27 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.543	0.48	0.48	4848	4848
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.20	46.26	462168	462770
wire	non noble metal	aluminium	7429-90-5	3.047	0.96	0.96	9572	9572
encapsulation	inorganic material	zincoxide	1314-13-2	1.404	0.44		4412	
	miscellaneous	miscellaneous	-	7.021	2.21		22059	
	plastics	epoxy resin	-	21.062	6.62		66176	
	inorganic material	silicondioxide	60676-86-0	110.927	34.85	44.12	348526	441173
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11751	11751
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4463	4474
solder	non noble metal	tin	7440-31-5	0.032	0.01		102	
	noble metal	silver	7440-22-4	0.040	0.01		127	
	non noble metal	lead	7439-92-1	1.544	0.49	0.51	4851	5080
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.03	6.04	60254	60332
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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